

SSC8130GN4

N-Channel Enhancement Mode MOSFET

Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	l _D
30V	+20V	4mΩ@10V	60A
	<u> </u>	6mΩ@4V5	00A

> Description

This SSC8130GN4 uses advanced trench technology to provide excellent RDSON and low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔVDS + Rg Tested!

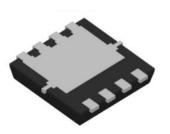
Applications

- DC/DC converters
- Power Supplies
- Motor Drive Control
- Synchronous rectification

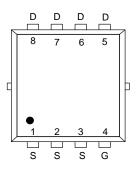
> Ordering Information

Device	Package	Shipping	
SSC8130GN4	PDFN3.3X3.3-8L	5000/Reel	

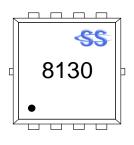
Pin configuration



PDFN3.3X3.3-8L (Bottom View)



Pin Configuration (Top View)



Marking



Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

Symbol	Parameter	Ratings	Unit		
V_{DSS}	Drain-to-Source Volta	Drain-to-Source Voltage		V	
V_{GSS}	Gate-to-Source Volta	Gate-to-Source Voltage		V	
	Ocation of Brain Ocated	T _C =25℃	60	^	
I _D	Continuous Drain Current d	T _C =100°C	35	A	
	Ocation of Brain Ocasa (T _A =25℃	23	Δ.	
IDSM	Continuous Drain Current ^a	T _A =70°C	17	Α	
I _{DM}	Pulsed Drain Current b		250	Α	
L	P_D Power Dissipation c $ T_C=25^{\circ}C $ $T_C=100^{\circ}C $	Tc=25°C	29	147	
Pb		11.6	W		
D.	Power Dissipation ^a	T _A =25℃	3.6	107	
P _{DSM}		T _A =70°C	2.3	W	
I _{AS}	Avalanche Current b L=0.5mH Single Pulse		25	Α	
Eas	Avalanche Energy ^b L=0.5mH Single Pulse		156	mJ	
TJ	Operation junction temperature		-55~150	°C	
T _{STG}	Storage temperature range		-55~150	℃	

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance a	35	°C/W
R ₀ JC	Junction-to-Case Thermal Resistance	4.3	C/ VV

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

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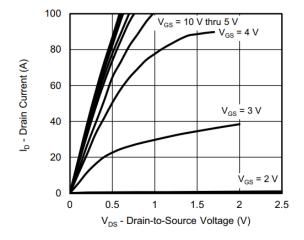


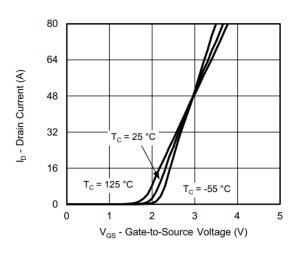
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250µA	30			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250uA$	1	1.7	3	V
Drain-Source On-Resistance	D	$V_{GS} = 10V, I_D = 20A$ $V_{GS} = 4.5V, I_D = 10A$		4	5.5	mΩ
Diam-Source On-Resistance	KDS(on)			6	8	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	lgss	$V_{GS} = \pm 20V$, $V_{DS} = 0V$			±100	nA
Transconductance	G _{FS}	V _{DS} = 5V, I _D = 10A		16		S
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 10A		0.8	1.3	V
Input Capacitance	Ciss	\/ 45\/ \/ O\/		2350		
Output Capacitance	Coss	$V_{DS} = 15V$, $V_{GS} = 0V$, $f = 1MHz$		280		pF
Reverse Transfer Capacitance	C _{RSS}	I = IIVIIIZ		260		
Total Gate Charge	Q _G	\\ 40\\\\\ 45\\		26		
Gate to Source Charge	Q _{GS}	$V_{GS} = 10V, V_{DS} = 15V,$ $I_{D} = 20A$		12		nC
Gate to Drain Charge	Q _{GD}	I _D = 20A		5.4		
Turn-on Delay Time	T _{D(ON)}			15		
Rise Time	Tr	V _{GS} = 10V, V _{DS} = 15V, R _L		7		
Turn-off Delay Time	T _{D(OFF)}	$=3\Omega$, $R_G=1\Omega$,		25		ns
Fall Time	Tf			6		
Diode Recovery Time	Trr	I _F =10A, di/dt=100A/us		40		ns
Diode Recovery Charge	Qrr	I _F =10A, di/dt=100A/us		55		nC

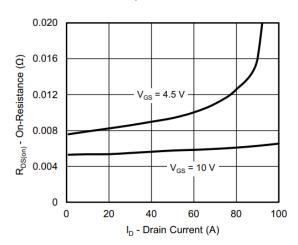


➤ Typical Performance Characteristics (T_A=25°C unless otherwise noted)

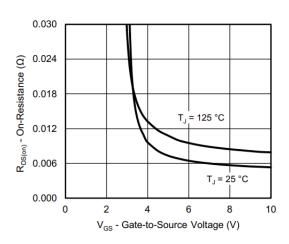




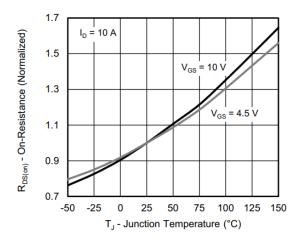
Output Characteristics



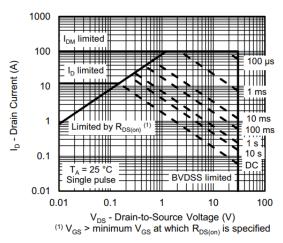
Transfer Characteristics



On-Resistance vs. Drain Current



On-Resistance vs. Gate-to-Source Voltage

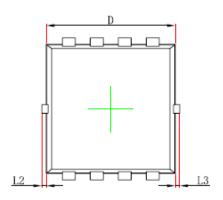


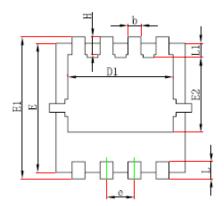
On-Resistance vs. Junction Temperature

Safe Operating Area



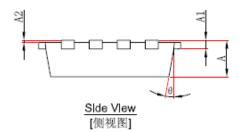
> Package Information





Top Vlew [顶视图]

Bottom View [背视图]

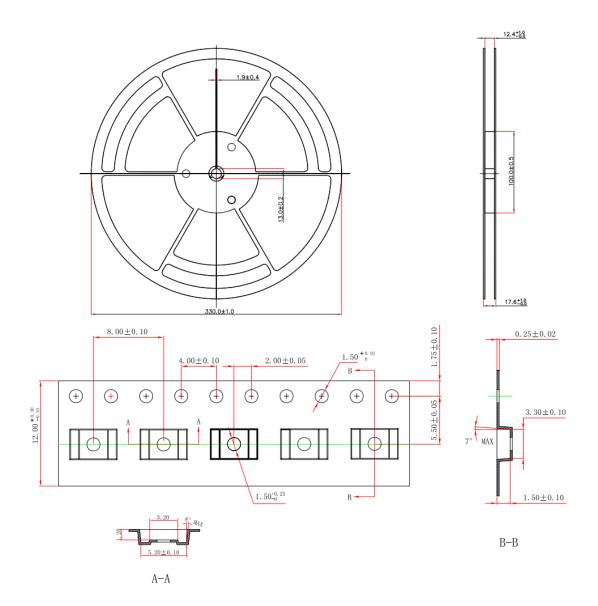


Package: PDNF3.3X3.3-8L

Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.650	0.850	0.026	0.033	
A1	0.152	REF.	0.006 REF.		
A2	0~0	0.05	0~0	0.002	
D	2.900	3.100	0.114	0.122	
D1	2.300	2.600	0.091	0.102	
E	2.900	3.100	0.114	0.122	
E 1	3.150	3.450	0.124	0.136	
E2	1.535	1.935	0.060	0.076	
b	0.200	0.400	800.0	0.016	
е	0.550	0.750	0.022	0.030	
L	0.300	0.500	0.012	0.020	
L1	0.180	0.480	0.007	0.019	
L2	0~0.100		0~0	.004	
L3	0~0.100		0~0	.004	
Н	0.315	0.515	0.012	0.020	
θ	9°	13°	9°	13°	



Tape and Reel



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